

# MECHANICAL CASE OUTLINE PACKAGE DIMENSIONS

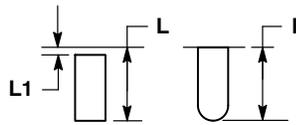
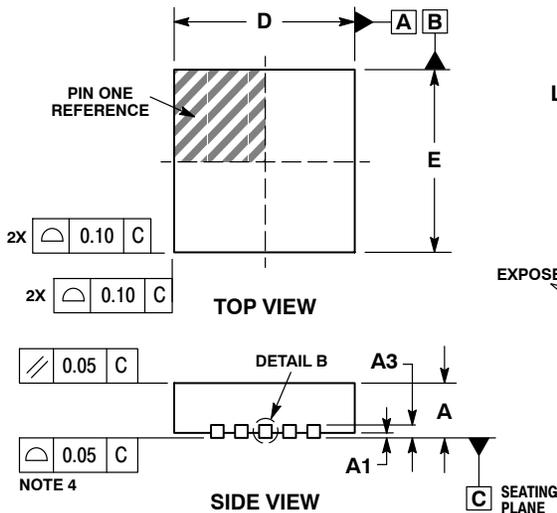
ON Semiconductor®



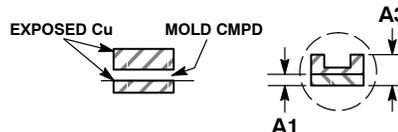
SCALE 2:1

QFN20 3x3, 0.4P  
CASE 485BC-01  
ISSUE O

DATE 15 OCT 2009



DETAIL A  
ALTERNATE TERMINAL  
CONSTRUCTIONS

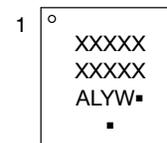


DETAIL B  
ALTERNATE  
CONSTRUCTIONS

- NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
  2. CONTROLLING DIMENSION: MILLIMETERS.
  3. DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.30mm FROM TERMINAL.
  4. COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.

DIM	MILLIMETERS	
	MIN	MAX
A	0.80	1.00
A1	---	0.05
A3	0.20 REF	
b	0.15	0.25
D	3.00 BSC	
D2	1.70	1.90
E	3.00 BSC	
E2	1.70	1.90
e	0.40 BSC	
K	0.30 REF	
L	0.20	0.40
L1	0.00	0.15

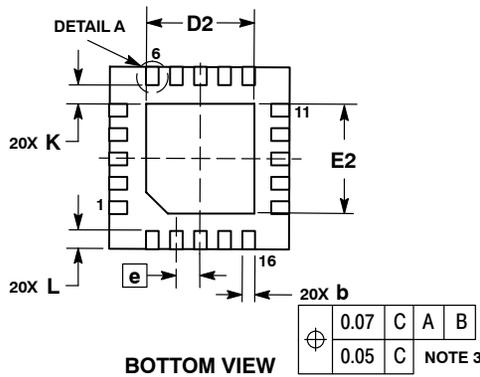
### GENERIC MARKING DIAGRAM\*



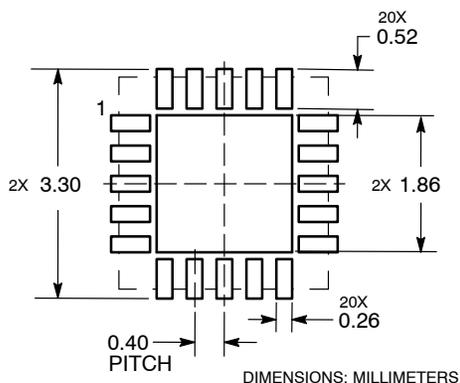
- XXXX = Specific Device Code
- A = Assembly Location
- L = Wafer Lot
- Y = Year
- W = Work Week
- = Pb-Free Package

(Note: Microdot may be in either location)

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G", may or not be present.



### SOLDERING FOOTPRINT\*



\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

DOCUMENT NUMBER:	98AON46007E	Electronic versions are uncontrolled except when accessed directly from the Document Repository. Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red.
STATUS:	ON SEMICONDUCTOR STANDARD	
NEW STANDARD:		
DESCRIPTION:	QFN20 3X3, 0.4P	PAGE 1 OF 2

